

Mathias Ekpu

List of Publications by Year in descending order

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9
papers

170
citations

1937685

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1720034

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9
all docs

9
docs citations

9
times ranked

141
citing authors

#	ARTICLE	IF	CITATIONS
1	Reliability analysis of SnAgCu lead-free solder thermal interface materials in microelectronics. Soldering and Surface Mount Technology, 2021, ahead-of-print, .	1.5	2
2	Effect of Tensile Load on the Mechanical Properties of AlSiC Composite Materials using ANSYS Design Modeller. Nigerian Journal of Technological Development, 2021, 17, 301-305.	0.6	0
3	Effect of Elevated Temperatures on SAC305 Solder Alloy Thermal Interface Material in a Microelectronic Assembly. FUOYE Journal of Engineering and Technology, 2021, 6, .	0.2	1
4	Investigating the Reliability of SnAgCu Solder Alloys at Elevated Temperatures in Microelectronic Applications. Journal of Electronic Materials, 2021, 50, 4433-4441.	2.2	4
5	Fatigue life of lead-free solder thermal interface materials at varying bond line thickness in microelectronics. Microelectronics Reliability, 2014, 54, 239-244.	1.7	37
6	The effect of thermal constriction on heat management in a microelectronic application. Microelectronics Journal, 2014, 45, 159-166.	2.0	5
7	Finite element analysis of the effect of silver content for SnAgCu alloy compositions on thermal cycling reliability of solder die attach. Engineering Failure Analysis, 2013, 28, 192-207.	4.0	54
8	Numerical study on thermal impacts of different void patterns on performance of chip-scale packaged power device. Microelectronics Reliability, 2012, 52, 1409-1419.	1.7	51
9	Investigation of effects of heat sinks on thermal performance of microelectronic package. , 2011, , .		16